[Material declaration substance-related product conformity]

27 June 2023

Supplier declaration in accordance with the RoHS Directive 2011/65 / EU, RoHS Directive 2015/863/EU, and Article 33 of the REACH Regulation (EC) No 1907/2006 for purchased parts of Data Panel GmbH:

Data Panel GmbH is a global acting company and committed as part of the "supply chain" to comply with certain laws and regulations. From our suppliers we need, for the goods delivered to us, information about substances, which are limited by corresponding specifications.

We kindly ask you to complete this questionnaire and send it back to us.
However, an equivalent and individual supplier declaration for the following substance restrictions may also be used for the declaration. For technical questions on these topics, please contact our partner:

Mrs. Claudia Wild, Phone: +49 7191 47-4011;

claudia.wild@murrelektronik.de

Name of material/ product group	Material No./ Part No. of supplier	Material No./ Part No. Data Panel GmbH
Passive Splitter xDBm06-CAN	DP-40044-00-000	DP-40044-00-000
Passive Splitter xDBm06-CAN	DP-40044-06-000	DP-40044-00-001

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- **"RoHS II": Directive 2011/65/EU (RoHS II) for restricting the use of certain hazardous substances in electrical and electronic equipment**

Annex II substances which are subject to restrictions and their maximum permissible concentrations in the homogeneous material by weight:

0.1 %	Lead
0.1 %	Mercury
0.01 %	Cadmium
0.1 %	Hexavalent chromium
0.1 %	Polybrominated biphenyls (PBB)
0.1 %	Polybrominated diphenyl ethers (PBDE)
0.1 %	Bis(2-ethylhexyl) phthalate (DEHP)
0.1 %	Butyl benzyl phthalate (BBP)
0.1 %	Dibutyl phthalate (DBP)
0.1 %	Diisobutyl phthalate (DIBP)

☒ **Compliant (Mandatory requirement)**

☐ **Not RoHS relevant**

Applications exempted from the restriction in Article 4(1) (Annex III of Directive 2011/65/EU) should be indicated:

☐ **RoHS compliant without exemption**

☒ **RoHS compliant with exemption** (⟶ please indicate accordingly or tick the appropriate box):

Name of exemption (acc. Annex III Directive 2011/65/EU)		
6(a)	Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35 % lead by weight	X
6(b)	Lead as an alloying element in aluminium containing up to 0,4 % lead by weight	
6(c)	Copper alloy containing up to 4 % lead by weight	X
7(a)	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)	

7(c)-I	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound	
7(c)-II	Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher	
8(b)	Cadmium and its compounds in electrical contacts	
34	Lead in cermet-based trimmer potentiometer elements	
37	Lead in the plating layer of high voltage diodes on the basis of a zinc borate glass body	

- **"REACh": Regulation (EC) No. 1907/2006 concerning the Registration, Evaluation, Authorization and Restriction of Chemicals**

  The materials must comply with the requirements of Annex XIV and Annex XVII of Regulation (EC) No. 1907/2006 corresponding to the field of application listed there. **Products containing substances of the candidate list (SVHC = Substances of Very High Concern) in a concentration> 0.1% by weight in the homogeneous material are subject to the obligation to inform under Art. 33:** http://echa.europa.eu/candidate-list-table

  ☒ **Compliant (Mandatory requirement)**

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- **"China-RoHS 2": Norm SJ/T 11364-2014 (Recast) und GB/T 26572-2011; Regarding the requirements for electrical and electronic products (EEP) related to the manufacture, placing on the market and import for the Chinese trading area (China RoHS 2)**

  Marking and declaration of hazardous substances in electrical and electronic products (EEP) for the limit to be complied with 0.01% (w/w) for cadmium and 0.1% (w/w) for lead, mercury, hexavalent chromium, polybrominated biphenyls (PBB) and polybrominated diphenyl ethers (PBDEs) in the homogeneous material.

  ☐ **Compliant** ☒ **Compliant with EPUP*** ☐ **Not China RoHS relevant**

  *EPUP (**E**nvironmental **P**rotection **U**se **P**eriod)

  Exceeding the specified limit values must be declared in accordance with ST / J 11364-2014 in a declaration table, stating the material concerned:

  (→ Please indicate accordingly or tick the appropriate box)

	Hazardous substance (有害物質)					
Part Name 零件名稱	Lead (Pb) 铅	Mercury (Hg) 汞	Cadmium (Cd) 镉	Hexavalent Chromium (Cr (VI)) 六价铬	Polybrominated biphenyls (PBB) 多溴联苯	Polybrominated diphenyl ethers (PBDE) 多溴联苯醚
Component part PCB 组件部分 印刷电路板	X					
Connection Terminal/ Screws/ Electrical Contact 接线端子 / 拧 / 电接触	X					

O: Indicates that the content of the harmful substance in all homogeneous materials of the component part is below the limit defined in GB/T 26572.
O: 表明該有害物質在組成部分的所有均質材料的含量低於按GB/ T26572定義的限制。
X: Indicates that the content of the harmful substance in at least one homogeneous material of the component part exceeds the limit defined in GB/T 26572.
X: 表示該有害物質在組成部分中的至少一個均質材料的含量超過按GB / T26572定義的限制。

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- **"Halogen-free" according Standard IEC 61249-2-21; the International Electrotechnical Commission (IEC) defines Halogen-free on basis of chlorine and bromine levels**

  A product is considered to be halogen-free if the following limit values are met:

  900 ppm Chlorine

  900 ppm Bromine

  1’500 ppm Halogenes total

  Halogenated compounds are predominantly present in plastics for electronics products (e.g. as flame retardants), as well as in composites that are partially made of plastics.

  ☐ **Compliant** ☒ **Not compliant** ☐ **Not applicable**

- **"Lead-free" according Joint Industry Standard IPC J-STD-006B-Amendments 1&2 and IPC/JEDEC J-STD-609**

  Lead-free solder alloys are defined by IPC J-STD-006B with a lead content of not more than 0,07% (w/w) and the lead content in homogeneous material according to IPC / JEDEC J-STD-609 is not more than 0.1% (w/w)

  ☒ **Compliant** ☐ **Not compliant** ☐ **Not applicable**

6/27/2023	Data Panel Corp.	Anthony Otis
Date	Company	Company stamp / Signature